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Product Change Notification - KSRA-25BPKT420 (Convert To PDF)

Date:

27 Jul 2018

Product Category:

32-bit Microcontrollers

Affected CPNs:





Notification subject:

CCB 3467 Initial Notice: Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Notification text:

PCN Status:

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of a new lead frame with double ring plating on paddle for selected Atmel products of 58.85K wafer technology available in 48L TQFP (7x7x1.0mm) package at ASE assembly site using palladium coated copper with gold flash (CuPdAu) bond wire

Pre Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with single ring plating on paddle palladium coated copper (CuPd) Bond wire

Post Change:

Assembled at ASE Inc. Taiwan (ASE) using a lead frame with double ring plating on paddle using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)			
Wire material	CuPd	CuPdAu			
Die attach material	CRM-1076WA	CRM-1076WA			
Molding compound material	EME-G631H	EME-G631H			
Lead frame material	C7025	C7025			
Lead frame Surface	Ring	Double Ring			

Note: See attached lead frame comparison

Impacts to Data Sheet:

None or list the changes that will be identified in the data sheet.

Change Impact:

None

Reason for Change:

To improve on-time delivery performance and qualify a new lead frame with double ring plating on paddle.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

December 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2018					>	December 2018				3
Workweek	27	28	29	30	31		48	49	50	51	52
Initial PCN Issue Date				Χ							
Qual Report											Χ

Availability						
Final PCN Issue Date						X

Method to Identify Change:

Traceability code

Oualification Plan:

Please open the attachments included with this PCN labeled as PCN # Qual Plan.

Revision History:

July 27, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products

Attachment(s):

PCN_KSRA-25BPKT420_Qual_Plan.pdf Lead Frame Pre and Post Change Comparison.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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